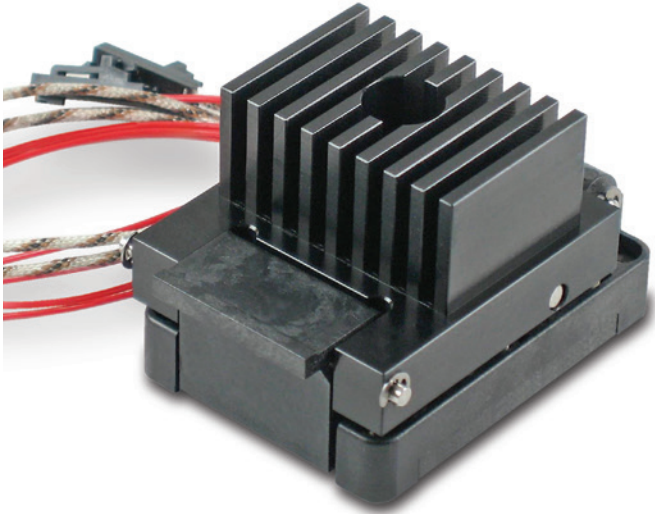


C-Series H-Pin Socket

Accelerated life testing solution



C Series Socket is a modular burn-in socket with clamshell-style lid. The small footprint outline allows for a best-in-class range of package accommodations, from 0.5 mm body size up to 12 mm and optimal socket density per burn-in board.

Utilizing the H-Pin in the C-Series socket provides market leading electrical performance for all reliability testing requirements.

The modularity provides unmatched design flexibility and ensures no sacrifices are made in delivering a complete solution without compromising performance or reliability.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

Benefits

- Design flexibility, in-house tooling and molds allow for lowest cost of test.
- Extensive catalog of standard components reduces cost and lead-time.
- ≥ 0.3 pitch accommodates a wide variety of application needs.
- Optimized thermal profile to end-use specification.

Feature options

- LCC, QFP, QFN, LGA, BGA, and WLCSP
- Spring-loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Package inserts for a variety of sizes
- High temperature materials for above 200 °C applications

C-Series socket specifications

Mechanical properties

- **Pitch:** ≤ 0.35 mm
- **Package size:**
LGA: 0.5 mm to 12 mm
BGA: 0.5 mm to 9 mm
- **Pin count:**
LGA: 625
BGA/QNF: 750
- **Temperature:** -55°C to 260°C

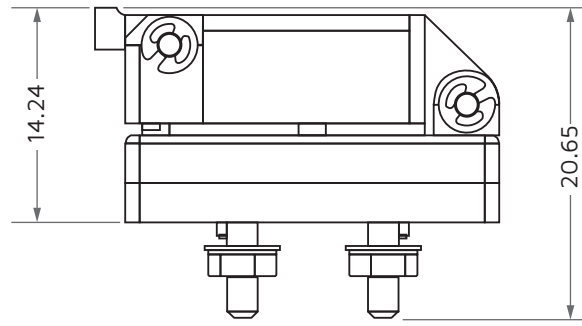
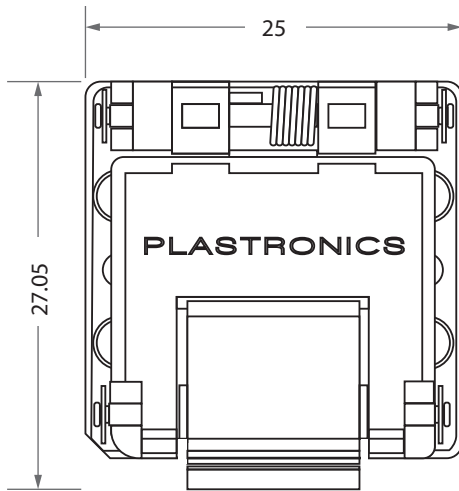
Electrical properties

- **Contact resistance:** 35 m Ω
- **Current carrying capacity:** up to 4 A

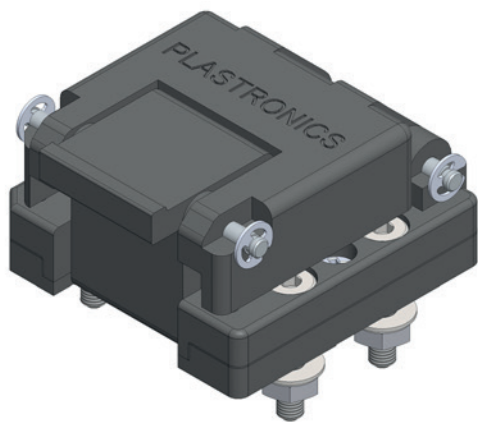
Materials

- **Contact:** BeCu/Au plated
- **Spring:** SS/Au plated
- **Socket:** Engineering plastics

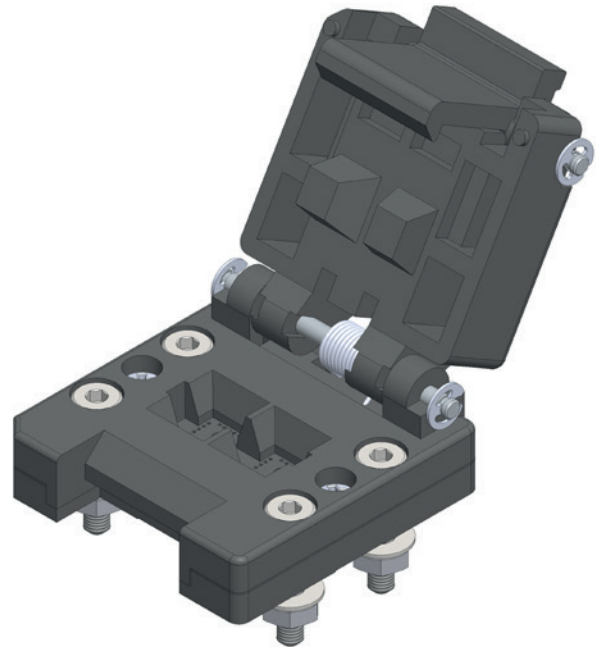
C-Series socket dimensions



Dimensions are in mm.



Heat sink, heater, and RTD



Spring-loaded plunger

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